H-310317

TITLE: SURFACE MOUNTING OF COMPONENTS

Abstract of the Disclosure

Surface mounting of components includes providing a substrate that has a first surface and a second surface. A portion of the first surface is coupled to a conductive layer that is patterned. A compliant layer is introduced to the first surface of the substrate and to the conductive layer. At least one aperture is formed in the compliant layer which extends to the surface of the conductive layer. Conductive material is introduced into the aperture(s). Solder couples the surface mount component to the compliant layer.